

## HEAT-STABLE HOT-MELT ADHESIVE COMPOSITION

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### Abstract of JP2000204334

**PROBLEM TO BE SOLVED:** To obtain the subject adhesive composition by incorporating a metal deactivator in a rubber-based hot-melt adhesive comprising a styrene-based thermoplastic rubber, a tackifying resin and a plasticizer so as to suppress its gelation under continuous heating, decline in its cohesive and adhesive power and discoloration and offensive odor emission and thus improve its thermal stability. **SOLUTION:** This hot-melt adhesive composition is obtained by incorporating 100 pts.wt. of a composition comprising 10-50 pts.wt. of a styrene-based thermoplastic rubber, 20-65 pts.wt. of a tackifying resin and 5-30 pts.wt. of a plasticizer with  $\geq 0.001$  pt.wt. of a hydrazine-based metal deactivator. The deactivator has such effect as to deactivate the deteriorative action of the residual metal catalyst on the styrene-based thermoplastic rubber, tackifying resin, plasticizer, etc., in this adhesive composition, leading to significantly improving this hot-melt adhesive composition in viscosity and hue change due to heat, and skinning, etc.

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